

AG35-Quecopen

Reference Design

LTE Module Series

Rev. AG35-Quecopen_Reference_Design_Rev.A

Date: 2018-06-05

Status: Released



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About the Document

History

Revision	Date	Author	Description
A	2018-06-05	Canice CHEN	Initial

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1 Reference Design

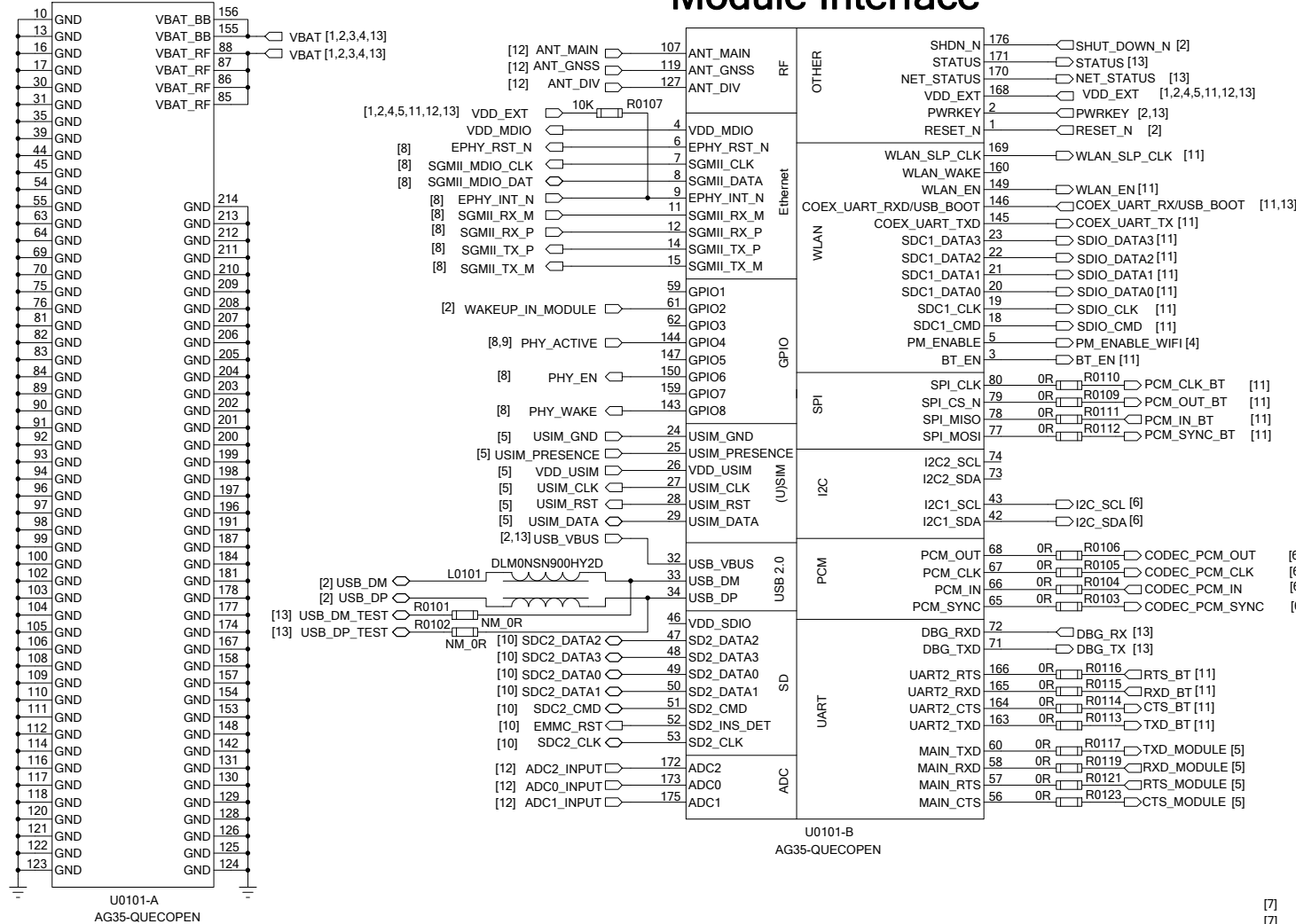
1.1. Introduction

This document provides the reference design for Quectel AG35-Quecopen module.

1.2. Schematics

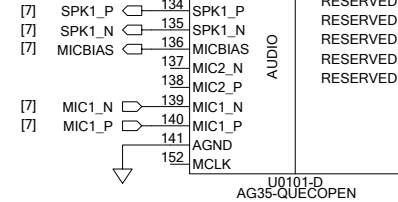
The schematics illustrated in the following pages are provided for your reference only.

Module Interface



Notes:

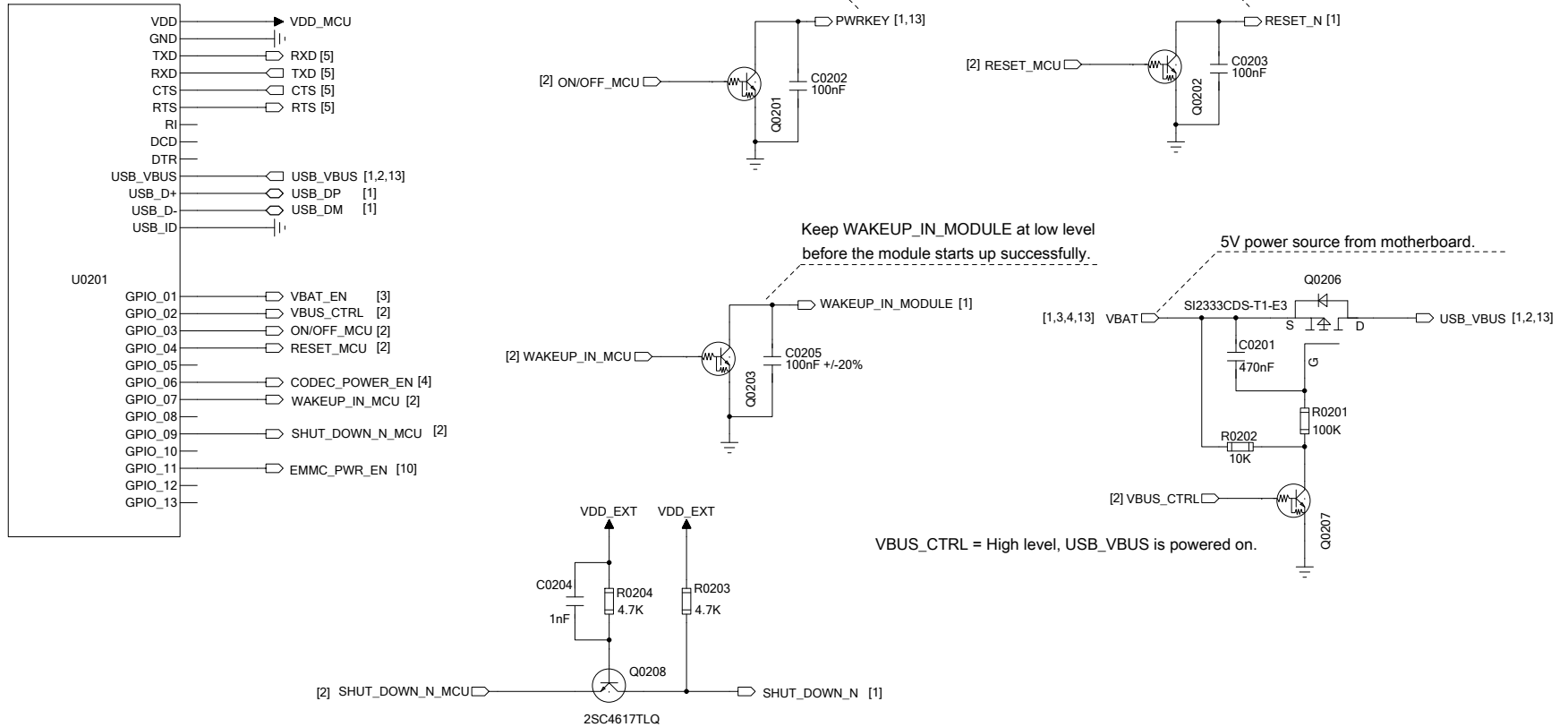
1. ADC pin cannot be directly connected to the power supply and must not exceed the voltage range.
2. It is recommended to reserve the test points for upgrading the firmware over USB interface and minimize the stub length of USB test signals.
3. Keep all RESERVED and unused pins unconnected, and ensure all GND pins are connected to the ground network.
4. PCM_***_BT network is used for communication with AF20 module. CODEC_PCM_*** network is used for communication with codec.
5. Pins 59, 65, 67, 80, 144, 145, 146, 147, 149 and 159 must be at low level before the module starts up successfully.
6. The module supports both Analog Audio and Digital Audio via PCM interface (pin 65 ~pin 68), but the two functions cannot be used synchronously.



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MCU Interface



Notes:

1. U0201 represents customer's MCU.
2. AG35-Quecopen can only work as a USB device and supports Full Speed and High Speed modes. To communicate with USB interface, MCU needs to support USB host or OTG function. The VBUS pins of MCU and AG35-Quecopen should be powered by a 5V power system for USB detection, and VBUS_CTRL is used to turn on/off VBUS power supply. When VBUS_CTRL is at high level, USB_VBUS will be powered on.
3. Transistor circuits (Q0201~Q0203, Q0208) are used for level translation.

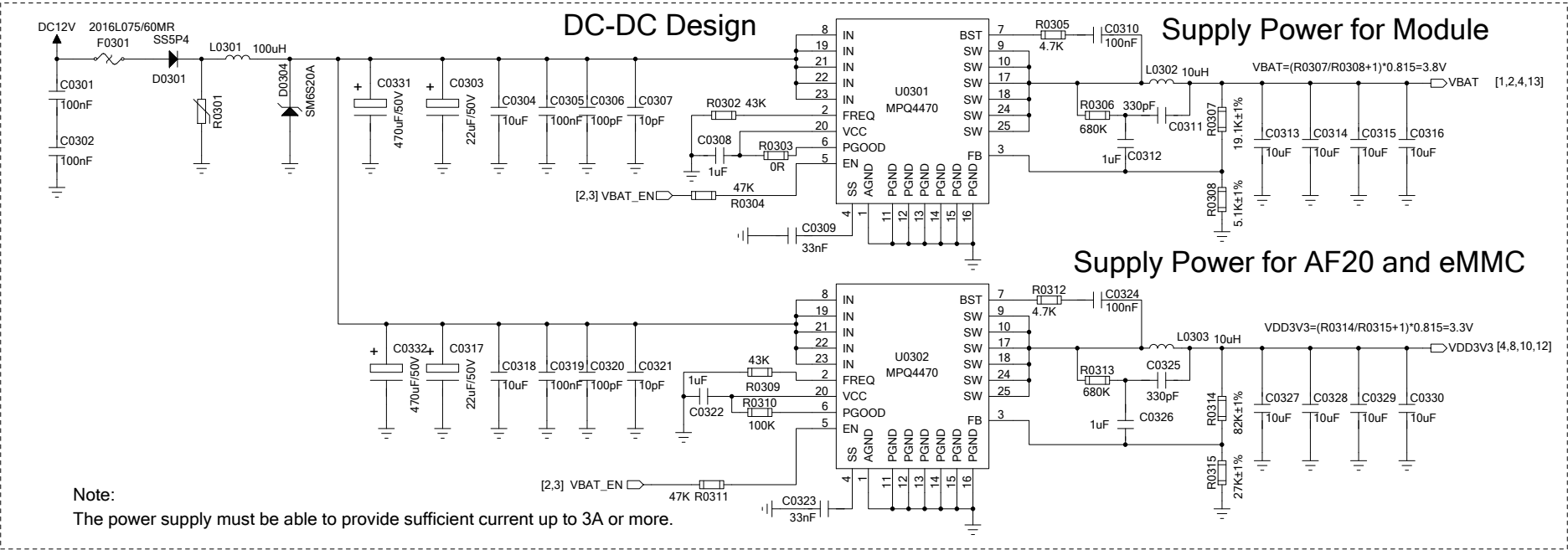
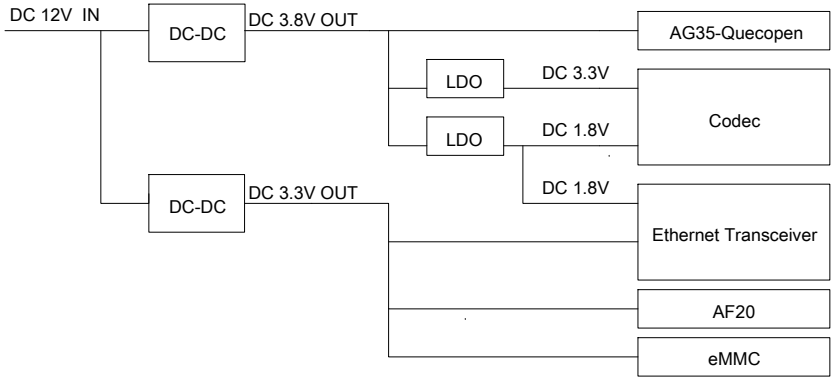
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Power Supply Design (Part 1)

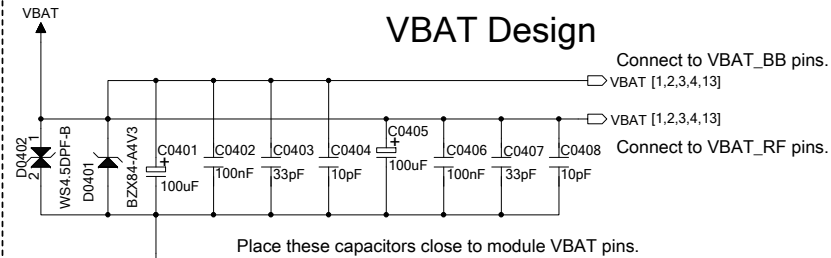
Block Diagram for DC-DC Application

A DC-DC converter is used to convert a high input voltage into 3.8V and 3.3V outputs, and then the LDOs will generate 3.3V and 1.8V typical voltages.

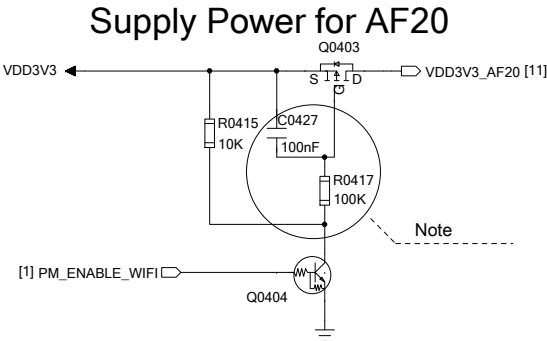


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Power Supply Design (Part 2)

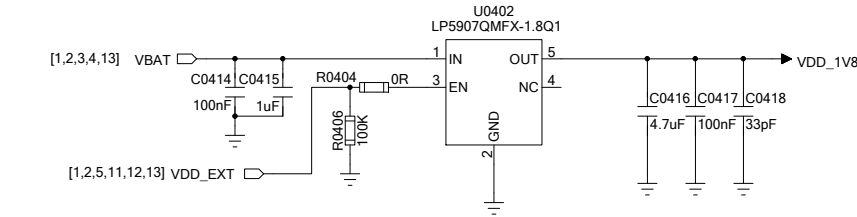
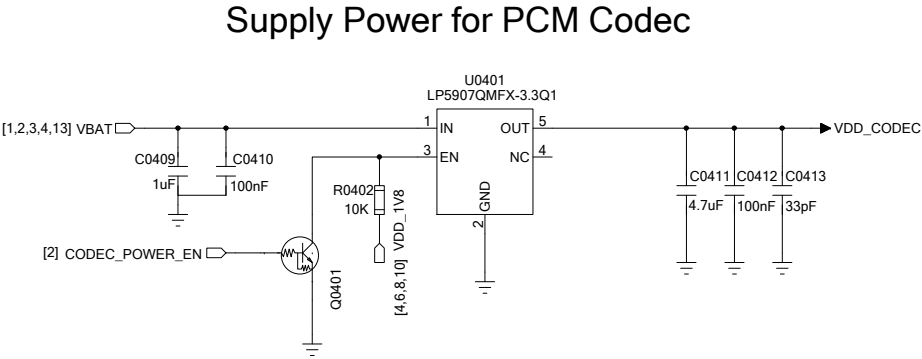


- Notes:
1. The power supply must be able to provide sufficient current up to 2A or more.
 2. VBAT should be routed in star mode to VBAT_BB and VBAT_RF pins.
 3. The recommended operating voltage of VBAT is 3.3V~4.3V.



Note:

The RC circuit, which is assembled with R0417 and C0427, is used to delay the start-up of MOSFET switch circuit.



Note:

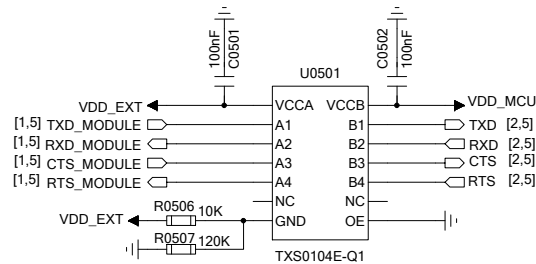
CODEC_POWER_EN must be at low level in order to ensure normal output voltage of VDD_CODEC.
If VDD_CODEC power supply needs to be switched off, please keep CODEC_POWER_EN at high level.

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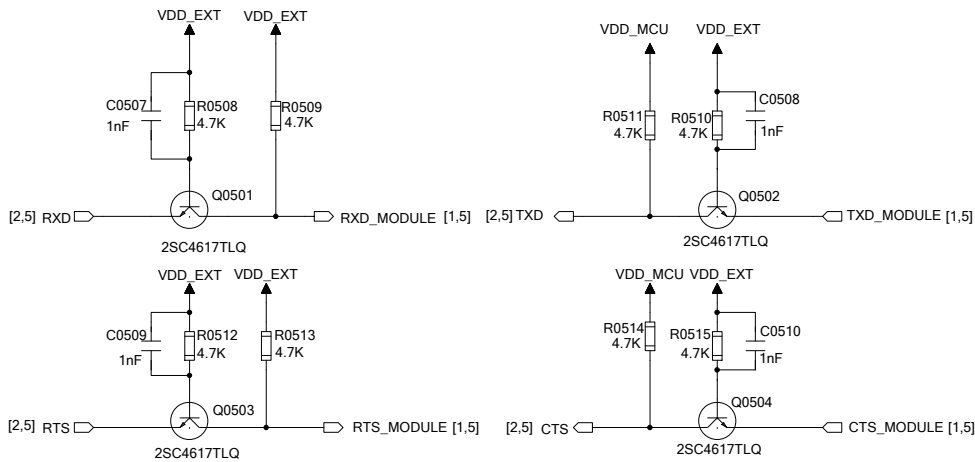
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UART and (U)SIM Design

UART Level Translation - IC Solution (Recommended)



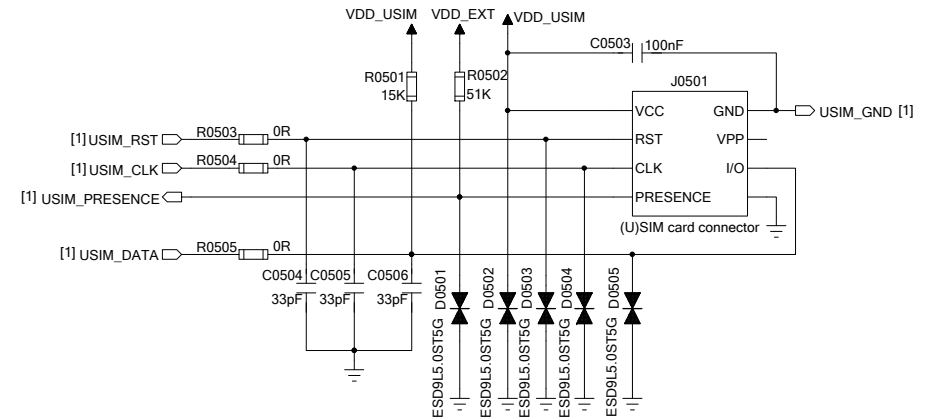
UART Level Translation - Transistor Solution



Notes:

1. It is recommended to use the voltage level translation IC solution.
The transistor circuit solution is not suitable for applications with high baud rates exceeding 460Kbps.
2. The supply voltage range of VCCA should not exceed that of VCCB. For more information about TXS0104E-Q1, please refer to the datasheet from TI.
3. If high baud rate is needed, it is highly recommended to install four 1nF capacitors (C0507/C0508 /C0509/C0510) on transistor circuits.

(U)SIM Interface



Notes:

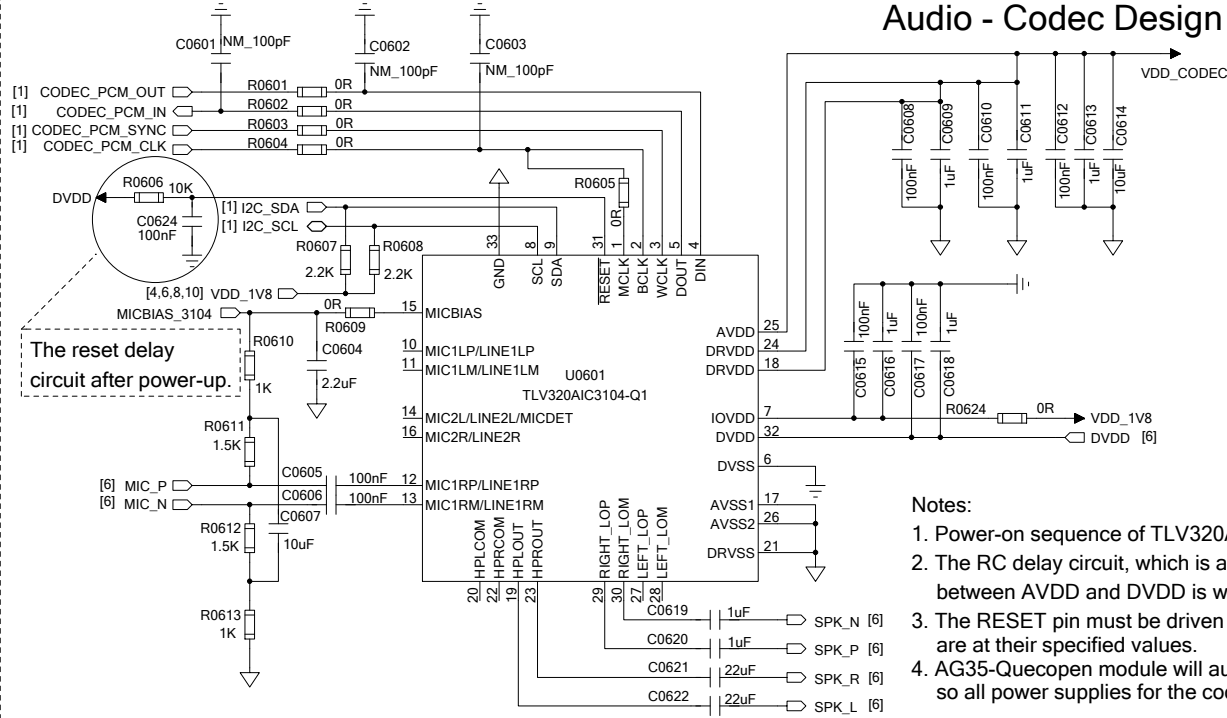
1. The decouple capacitor of VDD_USIM should be less than 1uF and must be near to (U)SIM card connector.
2. AG35-Quecopen module provides an input pin (USIM_PRESENCE) to detect whether the (U)SIM card exists or not. It supports both low level and high level detections.
For more details, please refer to *Quecotel_AG35-Quecopen_Hardware_Design*.
3. R0503-R0505 are applied to suppress the EMI spurious transmission and enhance the ESD protection.
4. It is recommended to take electrostatic discharge (ESD) protection measures near the (U)SIM card connector. The TVS diode with junction capacitance less than 10 pF must be placed as close as possible to the (U)SIM card connector.
5. R0501 can improve anti-jamming capability of the (U)SIM circuit and it should be placed close to the (U)SIM card connector.

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Audio Design (PCM Interface)

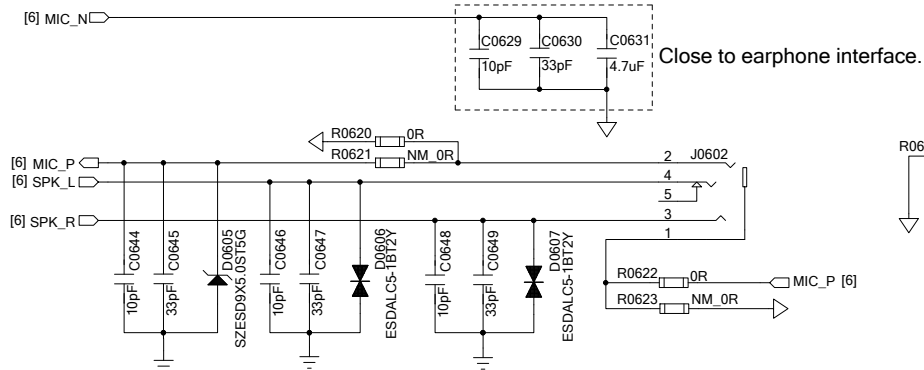
Audio - Codec Design



Notes:

1. Power-on sequence of TLV320AIC3104-Q1: IOVDD → AVDD/DRVDD → DVDD → Software Initialization
2. The RC delay circuit, which is assembled with C0623 and R0616, is used to ensure that the power-on time difference between AVDD and DVDD is within 5ms. For more details, please refer to TLV320AIC3104-Q1 datasheet.
3. The RESET pin must be driven at low level for at least 10ns after all power supplies for TLV320AIC3104-Q1 are at their specified values.
4. AG35-Quecopen module will automatically initialize the codec via I2C interface after it is turned on successfully, so all power supplies for the codec need to be turned on before that.

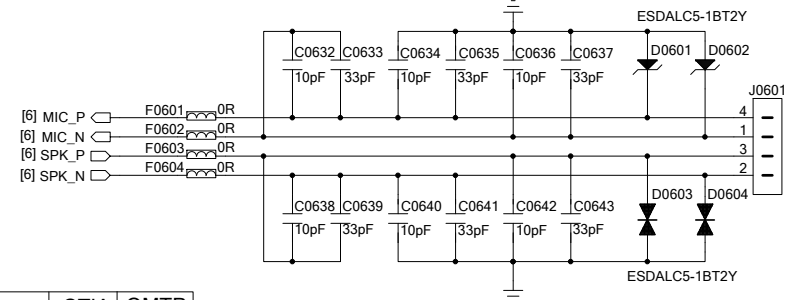
Audio - Earphone Application



Notes:

1. The analog output only drives earphone and handset. For larger power loads such as speakers, the design for an audio power amplifier should be added.
2. The maximum capacitive loading for speaker is 330 pF and the maximum capacitive loading for microphone is 250 pF.

Audio - Handset Application



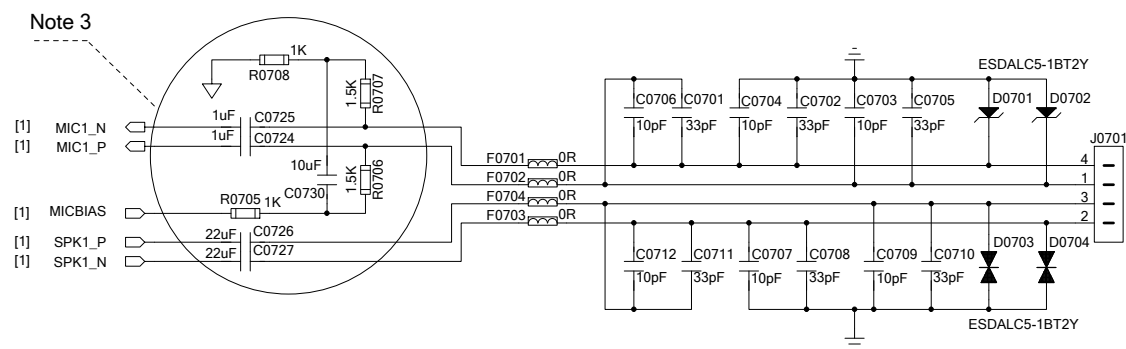
	CTIA	OMTP
R0621/R0623	NM	M
R0620/R0622	M	NM

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Audio Design (Analog Interface)

Audio - Handset Application



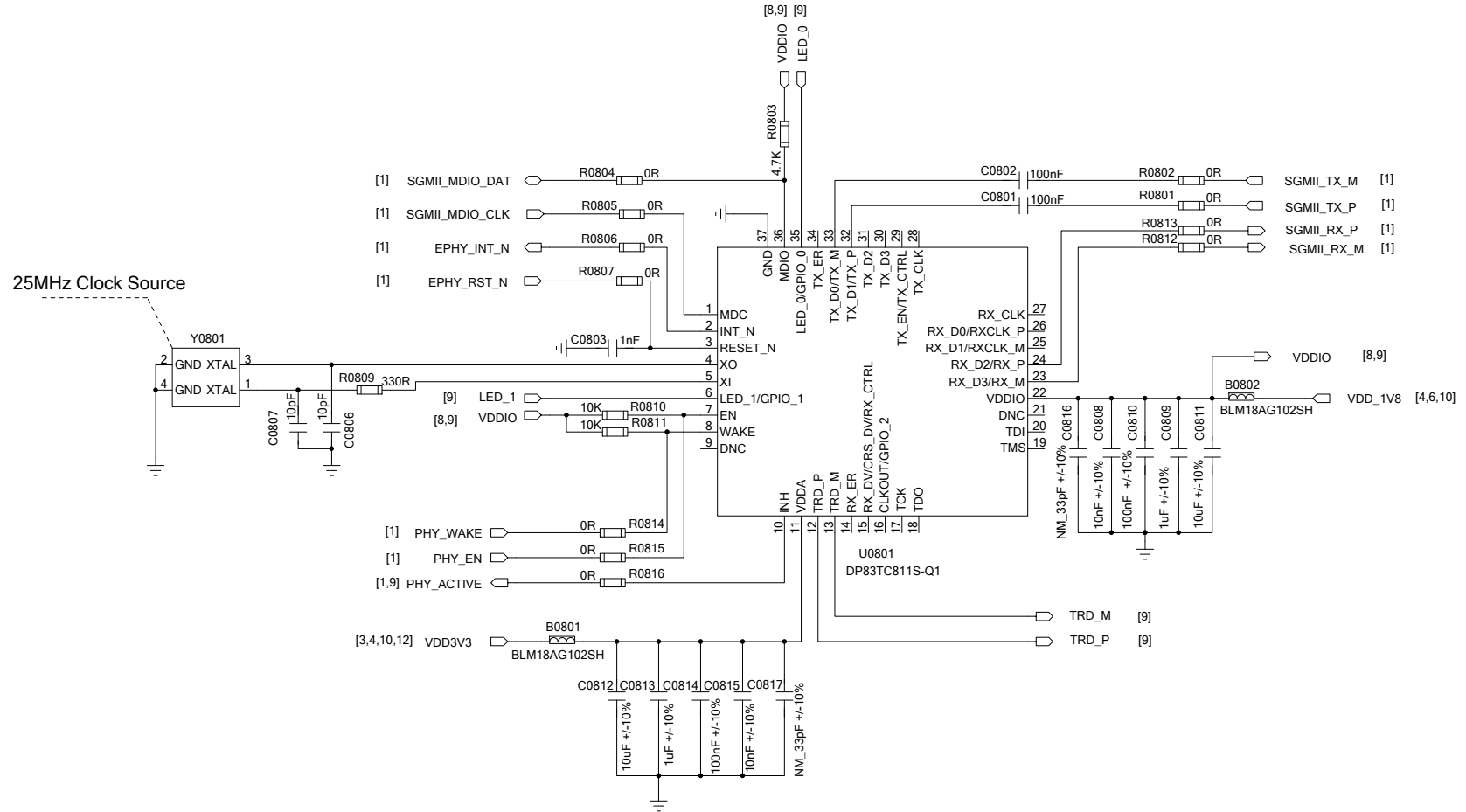
Notes:

1. The analog output only drives handset. For larger power loads such as speakers, the design for an audio power amplifier should be added.
2. The maximum capacitive loading for speaker is 330 pF and the maximum capacitive loading for microphone is 250 pF.
3. The analog output and input interface circuits should close to AG35-Quecopen.

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Ethernet Transceiver Design (Part 1)



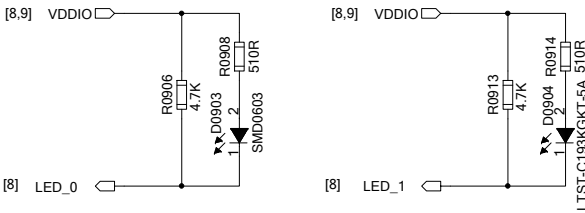
Note:
SGMII interface for DP83TC811S-Q1 Ethernet transceiver function is still under development.

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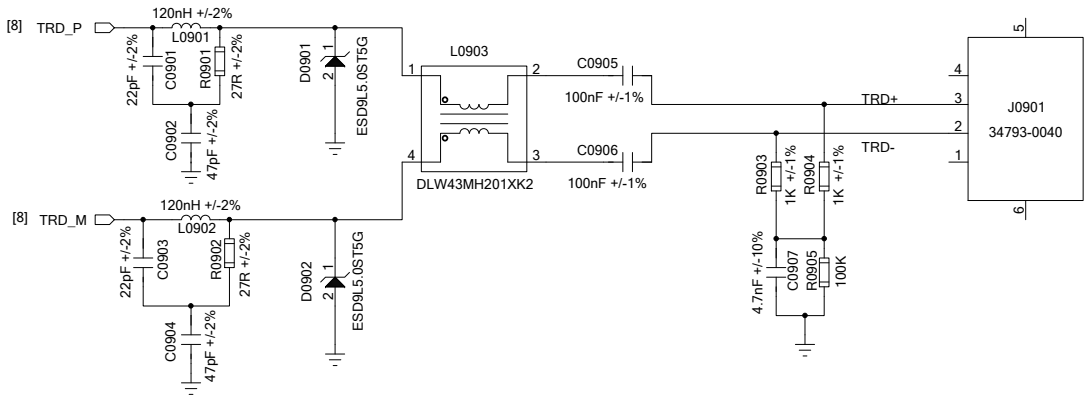
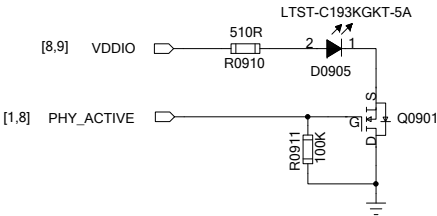
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Ethernet Transceiver Design (Part 2)

Link Rate Indication LEDs

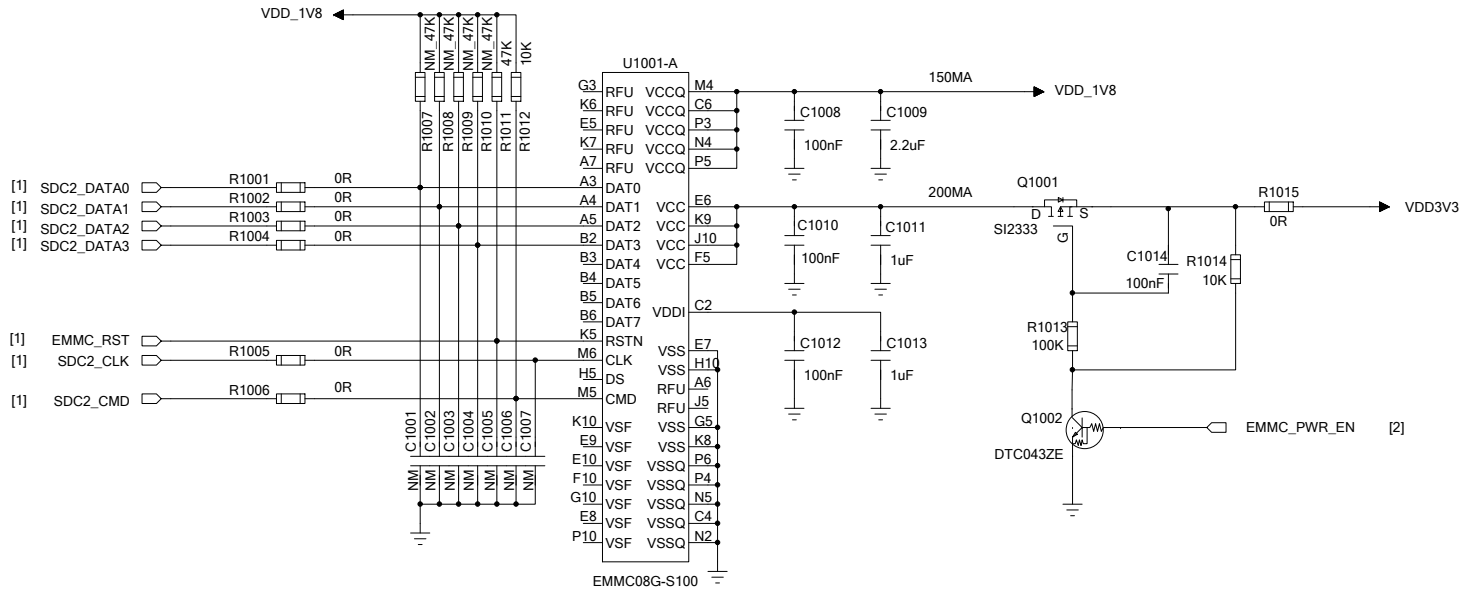
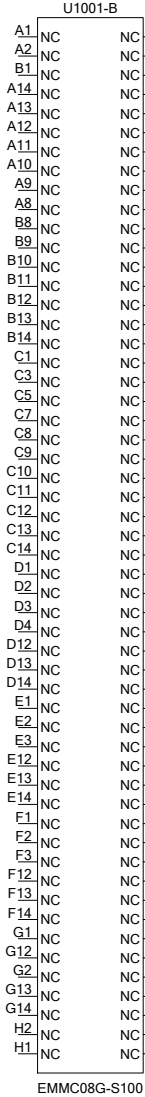


Operation Status Indication LED



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eMMC Design

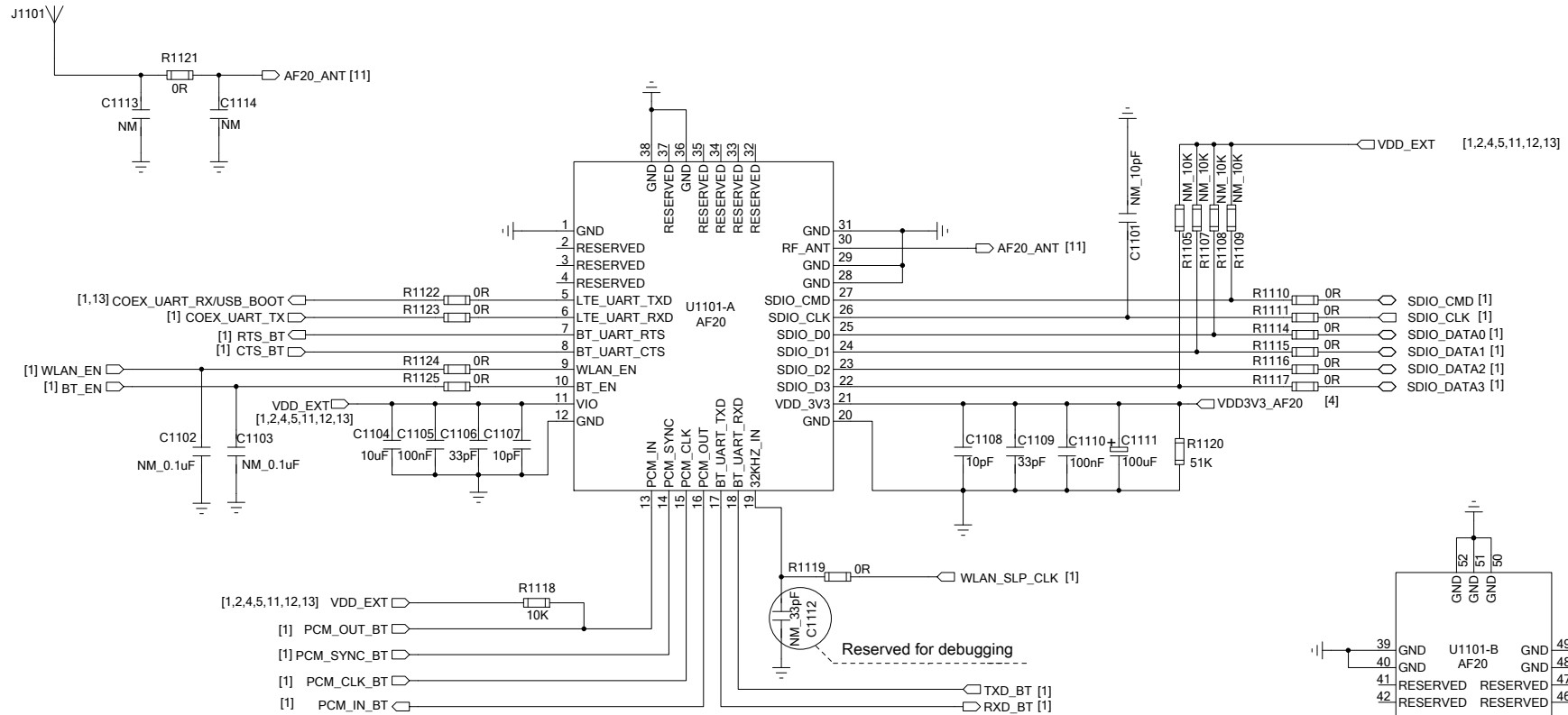


- Notes:
- AG35-Queopen supports the following eMMC models: eMMC08G-S100, SDINBDG4-8G-I and MTFC4GMDEA-4M IT.
 - Typical value of power filter capacitors:
- | Model | C1008 | C1009 | C1010 | C1011 | C1012 | C1013 |
|------------------|-------|-------|-------|-------|-------|-------|
| eMMC08G-S100 | 100nF | 2.2uF | 100nF | 1uF | 100nF | 1uF |
| SDINBDG4-8G-I | 100nF | 4.7uF | 100nF | 4.7uF | 100nF | 1uF |
| MTFC4GMDEA-4M IT | 100nF | 2.2uF | 100nF | 2.2uF | 100nF | 1uF |
- For more details, please refer to the datasheet of eMMC devices.
 - SDIO2 interface of AG35-Queopen supports both SD card and eMMC, but the two functions cannot be used synchronously. Customers can select SD card or eMMC according to application demands.

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AF20 Design

AF20 Antenna Circuit



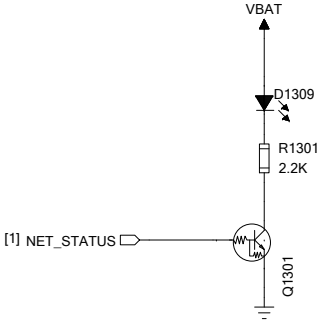
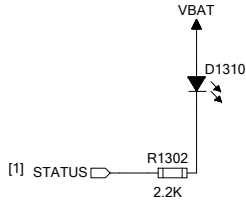
Notes:

1. Keep all RESERVED and unused pins unconnected.
2. The impedance of the SDIO data signal traces must be controlled as 50Ω when routing.
3. SDIO data lines should be shielded by ground; SDIO_CMD and SDIO_CLK signal lines should be shielded by ground separately.
4. It is recommended to use PI type AF20 antenna circuit, thus ensuring convenient subsequent debugging.
5. The impedance of RF signal trace must be controlled as 50Ω when routing.

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Indicators and Test Points

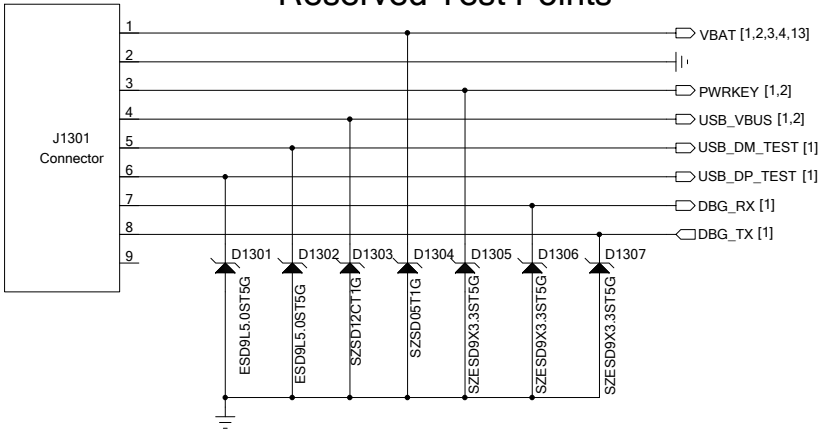
Indicators



Notes:

1. The STATUS is an open drain output pin, and its drive current is less than 0.9mA.
2. For more details about STATUS and NET_STATUS, please refer to *Quectel_AG35-Quecopen_Hardware_Design*.
3. If the current consumption is required as low as possible when the device is in sleep, replace the power supply of indicators with a controllable one.
Turn off the power when the module enters into sleep mode.

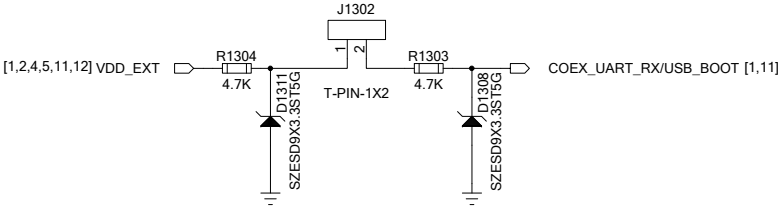
Reserved Test Points



Notes:

1. Both USB and debug UART interfaces are reserved for software debugging.
2. USB interface also can be used to upgrade firmware.
3. Keep USB test points as close as possible to USB pins.
Junction capacitance of ESD protection devices on USB data lines might influence the signal, please pay attention to it. Typically, the capacitance should be less than 1pF.
4. The debug interface supports 1.8V power domain.
A level translator should be used if the power domain of customers' application is 3.3V.

USB_BOOT for Download



Note:

COEX_UART_RX/USB_BOOT is kept open by default and the module will be forced into download mode quickly when COEX_UART_RX/USB_BOOT is at high level.

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